# **Bluetooth Module Datasheet**

Model: SJR-BTM356

**Version: V1.2** 

2022-04-07

Sky Jiarun Technologies Co., Ltd.

Tel: (0755)85279490

E-mail: sales@tianjiarun.com

Web: www.tianjiarun.com

**Baoan, Shenzhen** 

## **List of Contents**

1 Introduction	3
2 Key Features	3
3 Applications	4
4 Block Diagram	4
5 General specifications	4
6 Module Package Information	5
6.1 Pinout Diagram and package dimensions	5
6.2 Module Pin descriptions	6
7 Electrical Characteristics	10
7.1 Absolute Maximum Ratings	10
7.2 Recommended Operating Conditions	10
8 Recommended reflow temperature profile	11

### 1 Introduction

**Sky Jiarun Technologies** introduces the pioneer of the Bluetooth 5.3 modules SJR-BTM356 which is a high performance, cost effective, low power and compact solution. The Bluetooth module provides a complete 2.4GHz Bluetooth system based on the QCC3056 WLCSP chipset which is a single chip radio and baseband IC for Bluetooth 2.4GHz systems. This module is fully qualified single-chip dual mode Bluetooth@v5.3 system.

### 2 Key Features

#### BTM356(QCC3056) Features

- Qualified to Bluetooth v5.3 specification
- Dual 120 MHz Qualcomm® Kalimba™ audio DSPs
- 32/80 MHz Developer Processor for applications
- Firmware Processor for system
- Flexible QSPI flash programmable platform
- High-performance 24bit audio interface
- Digital and analog microphone interfaces
- Flexible PIO controller and LED pins with PWM support
- Serial interfaces: UART, Bit Serializer (I<sup>2</sup> C/SPI), USB 2.0
- Advanced audio algorithms
- Active Noise Cancellation: Hybrid, Feedforward, and Feedback modes, using Digital or Analog Mics, enabled using license keys available from Qualcomm®
- Qualcomm® aptX™ and aptX HD Audio
- 1 or 2 mic Qualcomm® cVc™ headset speech processing
- Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger

#### **Application subsystem**

- Dual-core application subsystem 32/80 MHz operation
- 32-bit Firmware Processor (reserved for system use) executes:
  - Bluetooth upper stack
  - Profiles
  - House-keeping code
- 32-bit Developer Processor executes: Developer applications
- Both cores execute code from external flash memory using QSPI clocked at 32 MHz or 80 MHz
- On-chip caches per core enable optimized performance and power consumption

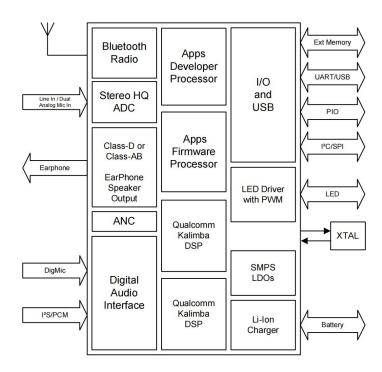
#### **Bluetooth subsystem**

- Qualified to Bluetooth v5.3 specification including 2 Mbps Bluetooth Low Energy and Bluetooth Low Energy Isochronous Channels
- Qualcomm® Bluetooth High Speed Link
- Single ended antenna connection with on-chip balun and Tx/Rx switch
- Bluetooth, Bluetooth Low Energy, and mixed topologies supported
- Class 1 support

## **3 Applications**

- Qualcomm TrueWireless™ stereo earbuds
- USB Dongle

## **4 Block Diagram**

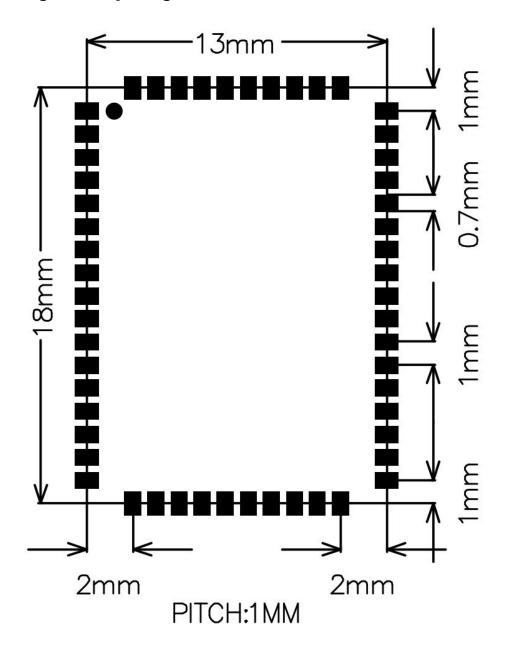


## **5 General specifications**

Model Name	SJR-BTM356
Product Description	Bluetooth 5.3 Class1.5 Module
Bluetooth Standard	Bluetooth 5.3
Chipset	QCC3056 WLCSP
Dimension	13mm x 18mm x 2.8mm
Operating Conditions	
Voltage	2.8~4.3V
Temperature	-40∼+85℃
Storage Temperature	-40∼+85℃
<b>Electrical Specifications</b>	
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
л /4 DQPSK Receive Sensitivity	-93dBm
8DPSK Receive Sensitivity	-87dBm

## **6 Module Package Information**

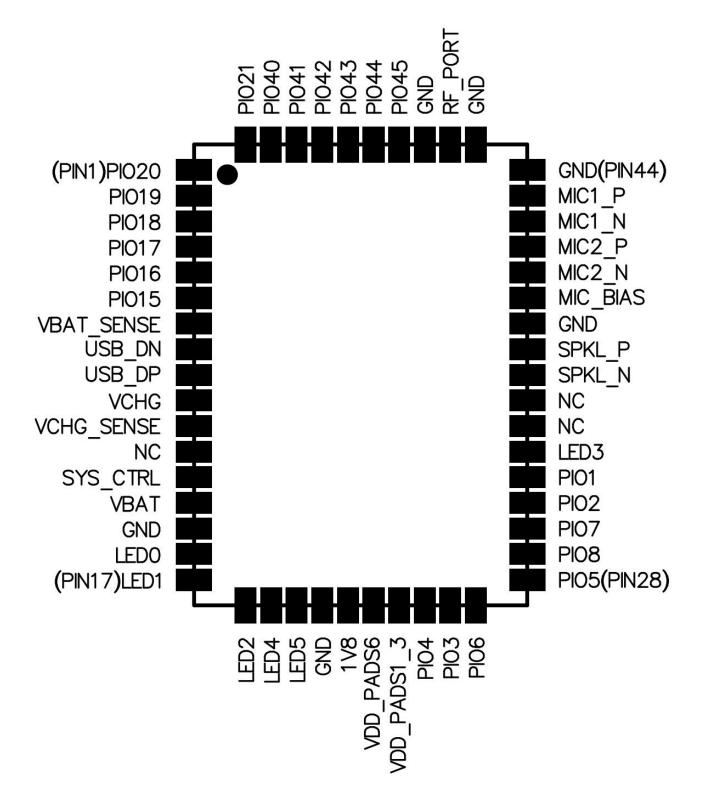
#### **6.1 Pinout Diagram and package dimensions**



Unit: MM

**Recommended PCB layout footprint** 

#### **6.2 Module Pin descriptions**



Pin#	Pin Name	Pin type	Description
		Digital: Bidirectional with	
1	PIO[20]	programmable strength internal	Programmable I/O line 20.
		pull-up/pull-down	
		Digital: Bidirectional with	Dua sua manala la 1/0 lina 40
2	PIO[19]	programmable strength internal	Programmable I/O line 19.
		pull- up/pull-down	
		Digital: Bidirectional with	Dragrammable I/O line 10
3	PIO[18]	programmable strength internal	Programmable I/O line 18.
		pull-up/pull-down	
		Digital: Bidirectional with	Dragrammable I/O line 17
4	PIO[17]	programmable strength internal	Programmable I/O line 17.
		pull- up/pull-down	
		Digital: Bidirectional with	Dragrammable I/O line 16
5	PIO[16]	programmable strength internal	Programmable I/O line 16.
		pull- up/pull-down	
		Digital: Bidirectional with	Draguera chia I/O line 45
6	PIO[15]	programmable strength internal	Programmable I/O line 15.
		pull- up/pull-down	
7	VBAT_SENSE	Analog	Battery voltage sense input.
۰	LICE DN	Divital	USB Full Speed device D- I/O. IEC-61000-4-2
8	USB_DN	Digital	(device level) ESD Protection
	1100.00	District	USB Full Speed device D+ I/O. IEC-61000-4-2
9	USB_DP	Digital	(device level) ESD Protection
10	VCHG	Supply	Charger input to Bypass regulator.
			Charger input sense pin. High
11	VCHG_SENSE	Analog	impedance. Connect VCHG_SENSE
			direct to SMPS_VCHG
12	NC	NC	NC
			Typically connected to an ON/OFF push
			button. If power is present from the
			battery and/or charger, and software has
	SYS_CTRL		placed the device in the OFF or
13		Digital input	DORMANT state, a button press boots
			the device. Also usable as a digital input
			in normal operation. No pull.
			Additional function:
			■ PIO[0] input only
14	VBAT	Supply	Battery voltage input.
15	GND	Ground	Ground
40	A10101// ED703	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
16	AIO[0]/LED[0]	output.	LED output.
47	A10141# ED141	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
17	AIO[1]/LED[1]	output.	LED output.
18	AIO[2]/LED[2]	Analog or digital input/ open drain	General-purpose analog/digital input or open drain

		output.	LED output.
40	ALOUALU EDIAL	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
19	AIO[4]/LED[4]	output.	LED output.
00	ALO(E)# ED(E)	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
20	AIO[5]/LED[5]	output.	LED output.
21	GND	Ground	Ground
22	1V8	Supply	1.8V voltage output.
23	VDD_PADS6	Supply	1.8 V/3.3 V PIO supply.
24	VDD_PADS1_3	Supply	1.8 V/3.3 V PIO supply.
		Digital: Bidirectional with	Programmable I/O line 4.
25	PIO[4]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MOSI[1]
		Digital: Bidirectional with	Programmable I/O line 3.
26	PIO[3]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[2]
		Digital: Bidirectional with	Programmable I/O line 6.
27	PIO[6]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MOSI[0]
		Digital: Bidirectional with	Programmable I/O line 5.
28	PIO[5]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[1]
		Digital: Bidirectional with	Programmable I/O line 8.
29	PIO[8]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_CLK
		Digital: Bidirectional with	Programmable I/O line 7.
30	PIO[7]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[0]
		Digital: Bidirectional with	Programmable I/O line 2.
31	PIO[2]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[3]
			Automatically defaults to
			RESET# mode when the
		Digital: Bidirectional with	device is unpowered, or
32	PIO[1]	programmable strength internal	in off modes.
		pull- up/pull-down	Reconfigurable as a PIO
			after boot.
			Alternative function:
	+		■ Programmable I/O line 1
33	AIO[3]/LED[3]	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
0.4	NO.	output.	LED output.
34	NC	NC	NC
35	NC	NC	NC
			Headphone/speaker differential output,
36	AUDIO_HP_N/ SPK_N	Analog	negative.
			Alternative function:

			■ Differential line output, negative
			Headphone/speaker differential output,
			positive.
37	AUDIO_HP_P/ SPK_P	Analog	Alternative function:
			■ Differential line output, positive
38	GND	Ground	Ground
39	AUDIO_MIC_BIAS	Analog	Mic bias output.
			Microphone differential 2 input, negative.
40	AUDIO_MIC2_N/ LINEIN_R_N	Analog	Alternative function:
			Differential audio line input right, negative
			Microphone differential 2 input, positive.
41	AUDIO_MIC2_P/ LINEIN_R_P	Analog	Alternative function:
			Differential audio line input right, positive
			Microphone differential 1 input, negative.
42	AUDIO_MIC1_N/ LINEIN_L_N	Analog	Alternative function:
			Differential audio line input left, negative
			Microphone differential 1 input, positive.
43	AUDIO_MIC1_P/ LINEIN_L_P	Analog	Alternative function:
			Differential audio line input left, positive
44	GND	Ground	Ground
45	GND	Ground	Ground
46	BT_RF	RF	Bluetooth transmit/receive.
47	GND	Ground	Ground
		Digital: Bidirectional with	Programmable I/O line 45.
48	PIO[45]	programmable strength internal	Alternative function:
		pull-up/pull-down	QSPI3_IO[3]
		Digital: Bidirectional with	Programmable I/O line 44.
49	PIO[44]	programmable strength internal	Alternative function:
		pull- up/pull-down	QSPI3_RAM_CS#
		Digital: Bidirectional with	Programmable I/O line 43.
50	PIO[43]	programmable strength internal	Alternative function:
		pull- up/pull-down	QSPI3_IO[1]
		Digital: Bidirectional with	Programmable I/O line 42.
51	PIO[42]	programmable strength internal	Alternative function:
		pull- up/pull-down	QSPI3_IO[2]
			D 11 1/0 !: 11
		Digital: Bidirectional with	Programmable I/O line 41.
52	PIO[41]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 41.  Alternative function:
52	PIO[41]		
52	PIO[41]	programmable strength internal	Alternative function:
52	PIO[41]	programmable strength internal pull- up/pull-down	Alternative function:  QSPI3_CLK
		programmable strength internal pull- up/pull-down  Digital: Bidirectional with	Alternative function:  QSPI3_CLK  Programmable I/O line 40.
		programmable strength internal pull- up/pull-down  Digital: Bidirectional with programmable strength internal	Alternative function:  QSPI3_CLK  Programmable I/O line 40.  Alternative function:  QSPI3_IO[0]
		programmable strength internal pull- up/pull-down  Digital: Bidirectional with programmable strength internal pull- up/pull-down	Alternative function:  QSPI3_CLK  Programmable I/O line 40.  Alternative function:

## **7 Electrical Characteristics**

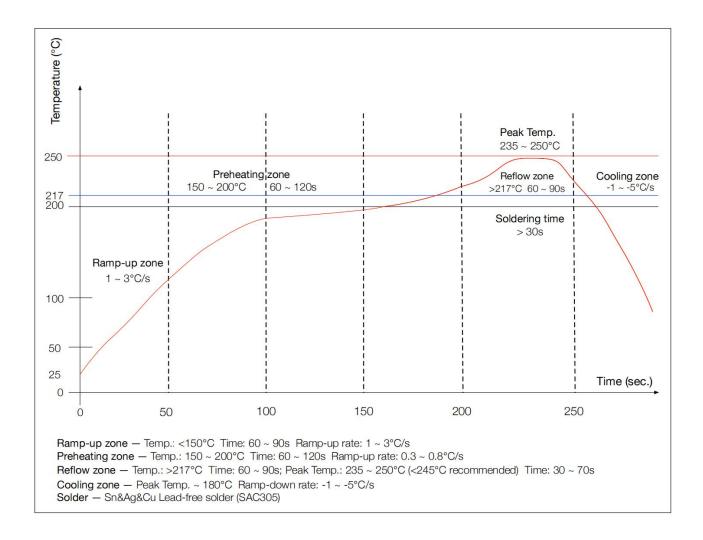
#### 7.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	<b>-40</b> ℃	+85℃

### 7.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	<b>-40</b> ℃	+85°C
Supply voltage: VBAT	+2.8V	+4.3V

### 8 Recommended reflow temperature profile



The module Must go through 125  $^{\circ}$ C baking for at least 9 hours before SMT AND IR reflow process!

若拆封后未立即上线,天嘉润科技建议让下次上线前务必以 125℃烘烤 9 小时以上!

### **Record of Changes**

Data	Revision	Description
2021-09-03	V1.0	Original publication of this document.
2021-11-21	V1.1	Update temperature.
2022-04-07	V1.2	Update bluetooth version.

#### **IMPORTANT NOTICE**

Sky Jiarun Technologies Co.,Ltd (SJR) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current. All products are sold subject to the SJR terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

SJR warrants performance of its products to specifications applicable at the time of sale in accordance with SJR's standard warranty. Testing and other quality control techniques are utilized to the extent SJR deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

In order to minimize risks associated with customer applications, adequate design and operating safeguards must be used by the customer to minimize inherent or procedural hazards. SJR products are not authorized for use as critical components in life support devices or systems without the express written approval of an officer of the company. Life support devices or systems are devices or systems that are intended for surgical implant into the body, or support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided, can be reasonably expected to result in a significant injury to the user. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

SJR assumes no liability for applications assistance or customer product design. SJR does not warrant or represent that any license, either express or implied, is granted under any patent right, mask work right, or other intellectual property right of SJR covering or relating or any combination, machine, or process in which such products or services might be or are used.

Tel: (0755) 85279490

Fax: (0755) 85279683

Web: www.tianjiarun.com

E-mail: sales@tianjiarun.com